Final Product/Process Change Notification

Document #:FPCN25070XB
Issue Date:16 Apr 2024

Title of Change:	Qualification of Alternate Lead Frame with C7025 base material for Specific QFN Devices at onsemi Seremban, Malaysia.
Proposed First Ship date:	23 Jul 2024 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or Nanthiya.Krishnasamy@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office or MohdAzizi.Azman@onsemi.com
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Product traceability will be maintained by date code.
Change Category:	Assembly Change
Change Sub-Category(s):	Material Change

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi Seremban, Malaysia	None

Description and Purpose:

onsemi is announcing the qualification of C7025 Base Material and adding HDS (HEASUNG DS) supplier for selected QFN devices in onsemi Seremban, Malaysia.

This change is implemented to mitigate potential supply disruption; customers are encouraged to urgently review this change in order to minimize any potential impact to their supply chain.

Upon implementation of this change, any of the qualified suppliers will be used to support demand.

	From (DCI)	**To (DCI or HDS)**	
Lead Frame Supplier	DCI	DCI	HDS
Base Material	EFTEC64T	EFTEC64T	C7025
Roughening	Non-Roughed	Non-Roughed	Roughed

Due to unexpected operation cease at DCI and their inability to support any last time buy orders, onsemi requires that customers approve this FPCN much faster than the standard notification period.

There is limited material currently available assembled with the current DCI lead frame. Therefore, the orders will be placed on hold as soon as the inventory of DCI lead frame material is depleted.

We are looking for your early approval to release orders and ship HDS lead frames prior to the proposed first ship date.

NOTE: There is no product marking change and product traceability will be maintained by lot and date code.

Reliability Data Summary:

QV DEVICE NAME: SZESD7451N2T5G
RMS: S83960
PACKAGE: XDFN2 1.0x0.6, 0.65P

Test	Specification	Condition	Interval	Results
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hrs	0/84
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre TC, uHAST, HAST for surface mount pkgs only		0/84
Temperature Cycling	JESD22-A104	Ta= -55°C to + 150°C	1000 cyc	0/84
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/84
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only		0/10
Solderability	JSTD002	Ta = 245°C, 5 sec		0/15
Physical Dimensions	JESD22-B120			

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
ESD7421N2T5G	SZESD7451N2T5G